

Title (en)
Wire wound electronic component and method of manufacturing the same

Title (de)
Drahtgewickeltes elektronisches Bauelement und Verfahren zu seiner Herstellung

Title (fr)
Composant électronique à fil enroulé et son procédé de fabrication

Publication
EP 0845792 A3 19990210 (EN)

Application
EP 97309130 A 19971113

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• JP 35281796 A 19961214

Abstract (en)
[origin: EP0845792A2] A wire wound electronic component of the present invention includes a bobbin having a core 1a having a substantially circular cross-section and rectangular flanges 1b formed at both ends of the core. A groove 2 is formed in each side of each flange 1b. A conductive film or external electrode 3 is formed on each flange 1b. A coil or wire 4 is wound round the core 1a and has a conductor protruding from opposite stripped ends thereof. The opposite ends 5 of the conductor are respectively received in the grooves 2 of the flanges 1b and connected to the conductive films 3. A coating or armor 6 is formed on the coil 4 and has a flat surface 6a. The coating 6 has a rectangular configuration complementary to the configuration of the flanges 1b. <IMAGE>

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Citation (search report)
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